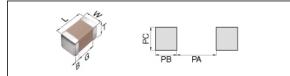


C1608X5R1E225K080AB (TDK item description : C1608X5R1E225KT****)

Applications		Commercial Grade
Feature	General	General (Up to 50V)
Series	C1608 [EIA CC0603]	





Size		
Length(L)	1.60mm +/-0.10mm	
Width(W)	0.80mm +/-0.10mm	
Thickness(T)	0.80mm +/-0.10mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.30mm Min.	
Recommended Land Pattern(PA)	0.70 to 1.00mm (Flow Soldering) 0.60 to 0.80mm (Flow Soldering)	Reflow Solderin
Recommended Land Pattern(PB)	0.80 to 1.00mm (Flow Soldering) 0.60 to 0.80mm (Flow Soldering)	Reflow Solderin
Recommended Land Pattern(PC)	0.60 to 0.80mm (Flow Soldering) 0.60 to 0.80mm (Flow Soldering)	Reflow Solderin
Recommended Slit Pattern(SD)		

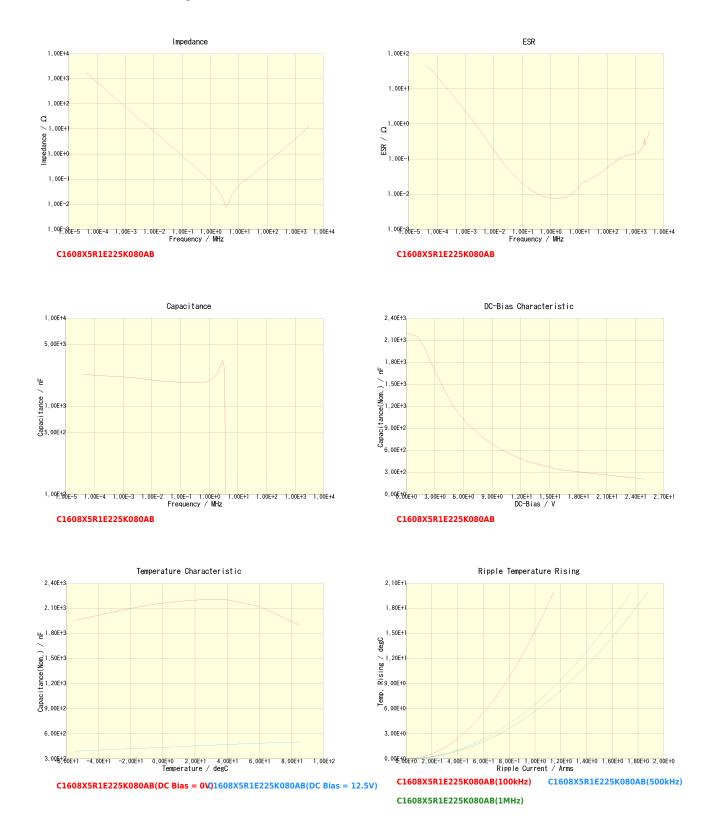
Electrical Characteristics				
Capacitance	2.2uF +/-10%			
Rated Voltage	25Vdc			
Temperature Characteristic	X5R(+/-15%)			
Dissipation Factor	10% Max.			
Insulation Resistance	227MΩ Min.			

Other			
Soldering Method	Reflow, Flow		
AEC Q200	No		
Packing	Punched (Paper)Taping [180mm Reel]		
Package Quantity	4000Pcs Min.		

•This PDF document was created based on the data listed on the TDK Corporation website. •All specifications are subject to change without notice.

C1608X5R1E225K080AB

Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



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